

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	1522	wafer with (temperature adj distribution)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:33	
2	BRS	L2	2040	wafer with temperature with distribution	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:34	
3	BRS	L3	431	2 and (heat adj2 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:35	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
4	BRS	L4	205	3 and (surface near3 temperature)	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:36	
5	BRS	L5	439	2 and ((heat adj2 treat\$4) with wafer)	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:36	
6	BRS	L6	208	5 and (surface near3 temperature)	USPAT; US-PGPUB; ; EPO; JPO; DERWENT; IBM_TDB	2004/01/22 18:38	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	L7	1	6 and (heat adj transfer adj plate)	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_T DB	2004/01/22 18:38	